

## **AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

### **LISTING OF CLAIMS**

1. (Currently Amended) A manufacturing method for an organic EL display which is provided with ~~an organic EL element and a semiconductor element which drives the~~ for driving an organic EL element on ~~for a display base board, pixel or a plurality of pixels, comprising the steps of:~~

~~the manufacturing method for an organic EL display comprising the step of disposing a~~ plurality of unit blocks having said semiconductor element ~~at a predetermined position of a display on a first base board;~~

disposing each unit block on a second base board such that each unit block corresponds to the pixel or the plurality of pixels formed thereon.

2. (Currently Amended) ~~Manufacturing~~ A manufacturing method for an organic EL display according to claim 1 ~~the unit block being formed such that said plural semiconductor elements are formed on a single crystal semiconductor base board in parallel, and this base board is divided.~~ , which is provided with a semiconductor element for driving an organic EL element for a pixel or a plurality of pixels, comprising the steps of:

disposing a plurality of unit blocks having said semiconductor element on a first base board, which is composed of a single crystalline semiconductor;

dicing the first base board so as to be divided per unit block; and

disposing each unit block on a second base board, such that each unit block corresponds to the pixel or the plurality of pixels formed thereon.

3. (Currently Amended) ~~Manufacturing~~ A manufacturing method for an organic EL display according to claim 1 comprising the steps of:

~~a concavity having a shape corresponding to the shape of the unit block being formed at a predetermined position of base board of display, the unit block being disposed at a predetermined position of the display base board by fitting unit block into this concavity in a liquid~~ such that each unit block corresponds to the pixel or the plurality of pixels formed on the second base board; and

disposing each unit block at a position where the concavity is formed in a liquid.

4. (Currently Amended) ~~Manufacturing~~ A manufacturing method for an organic EL display according to claim 1 ~~by arranging~~ comprising the steps of:

a hole which penetrates in ~~the~~ a thickness direction through the ~~display~~ second base board in ~~a predetermined position of the display base board,~~ and by being formed such that each unit block corresponds to the pixel or the plurality of pixels formed on the second base board;

introducing the unit block to ~~the~~ a position of said hole on one ~~surface~~ face of ~~display~~ the second base board by making ~~the~~ a pressure at ~~the~~ the one face of the ~~display~~ second base board ~~greater~~ higher than ~~the~~ a pressure at the other face, or by drawing ~~the~~ a liquid into said hole, the unit block being disposed at ~~a predetermined~~ the position of said hole on the display second base board.

5. (Currently Amended) ~~Manufacturing~~ A manufacturing method for an organic EL display according to claim 4 wiring being performed by using said hole.

6. (Currently Amended) ~~Manufacturing~~ A manufacturing method for an organic EL display according to claim 1 the unit block being introduced to be disposed ~~at a predetermined position of the display base board~~ by Coulomb attractive force such that each unit block corresponds to the pixel or the plurality of pixels formed thereon.

7. (Currently Amended) ~~Manufacturing~~ A manufacturing method for an organic EL display according to claim 1 characterized in disposing materials for an organic EL element ~~corresponding to the position of a pixel on display~~ for a pixel or a plurality of pixels on the second base board by an ink jet method.

8. (Currently Amended) ~~Manufacturing~~ A manufacturing method for an organic EL display according to claim 1 characterized in forming wiring ~~which is formed on display~~ above the second base board by an ink jet method.

9. (Currently Amended) ~~Manufacturing~~ A manufacturing method for an organic EL display according to claim 1 wherein the driving method ~~being~~ is active-matrix method.

10. (Currently Amended) Manufacturing method for an organic EL display according to ~~claim 9 scanning line, signal line, and power supply line terminals for connecting wiring inside the unit block of these wirings being formed on the display base board in advance, after terminals for connecting wirings on the display base board being formed at the position which contacts these terminals at the time of disposing on the display base board in the unit block, the unit block being disposed at a predetermined position on the display base board.~~ which is provided with a semiconductor element for driving an organic EL element for a pixel or a plurality of the pixels, comprising the steps of:

disposing a plurality of unit blocks having said semiconductor element and first connecting terminals which are connected to the semiconductor element on a first base board;

disposing wirings and second connecting terminals above a second base board;  
and

disposing each unit block on the second base board such that each unit block corresponds to the pixel or the plurality of pixels formed on the second base board and the first connecting terminals which are disposed on the unit block are connected with the second connecting terminals which are disposed on the second base board.

11. (Cancelled)

12. (Currently Amended) Manufacturing method for an organic EL display according to claim 11 10

the unit blocks having plural semiconductor elements for driving plural neighboring organic EL elements,

~~plural elements for each organic EL element being disposed such that the a~~  
planar shape of the unit block is polygonal and ~~is~~ the first connecting terminals are  
rotationally ~~symmetrical~~ symmetrically centered at ~~the a~~ a center of the polygon, and a  
number of corners of the polygon corresponds to a number of the semiconductors  
formed on the unit block.

13. (Currently Amended) Manufacturing method for a organic EL display according to claim 11 10

the unit blocks having plural semiconductor elements for driving plural neighboring organic EL elements, and

a planar shape of the unit block blocks being rectangular, ~~and plural~~ the first  
connecting terminals for each organic EL element being are disposed so as to be  
~~axisymmetric~~ axis symmetric with respect to center lines which are parallel with ~~the a~~  
longer side of the rectangle ~~and the center line which is parallel to the~~ or a shorter side  
of the rectangle.

14. (Currently Amended) Manufacturing method for an organic EL display according to claim ~~11~~ 10

the unit block having plural semiconductor elements for driving plural neighboring organic EL elements, and

a planar shape of the unit block being is polygonal, and plural terminals for each organic EL element being and the first connecting terminals are disposed along each diagonal lines of the polygon, and ~~the~~ a position of the first terminals on each of the diagonal lines being such that the ~~same terminal is on the same previous position after the rotation~~ first connecting terminals are connected to the same wiring when the unit block is disposed on the second base board and the wiring is formed.

15. (Original) Manufacturing method for an organic EL display according to claim 12 said polygon being an equilateral polygon.

16. (Original) Manufacturing method for an organic EL display according to claim 14 said polygon being an equilateral polygon.

17. (Currently Amended) ~~Manufacturing method for an organic EL display~~

~~according to claim 11~~ A manufacturing method for an organic EL display, which is provided with an organic EL element and a semiconductor element for driving the organic EL element for a pixel or a plurality of the pixels, comprising the steps of:

disposing each unit block on a base board such that each unit block corresponds to the pixel or the plurality of pixels formed on the base board,

each unit block having 3 semiconductor elements for driving 3 neighboring organic EL elements,

plural groups of organic EL ~~element~~ elements made of 3 pieces of neighboring organic EL elements such as red color light emitting, blue color light emitting, green color light emitting being disposed on ~~display the~~ base board, and

~~unit block having~~ each of the semiconductor ~~element-~~ elements for driving 3 pieces of neighboring organic EL elements being disposed at ~~the~~ a position which is ~~center of~~ centered relative to the 3 pieces of neighboring organic EL element per ~~each~~ group.



18. (Currently Amended) ~~Manufacturing method for an organic EL display according to claim 11~~ A manufacturing method for an organic EL display, which is provided with an organic EL element and a semiconductor element for driving the organic EL element for a pixel or a plurality of pixels, comprising the steps of:

disposing each unit block on a base board such that each unit block corresponds to the pixel or the plurality of pixels formed on the base board,

the unit block having plural semiconductor elements for driving plural neighboring organic EL elements, and

plural groups of organic EL ~~element~~ elements made of each 6 pieces of neighboring organic EL elements such as 2 pieces of red color light emitting, 2 pieces of blue color light emitting, 2 pieces of green color light emitting being disposed on ~~display~~ the base board,

each unit block having semiconductor ~~element~~ elements for driving 6 pieces of neighboring organic EL elements being disposed at ~~the a~~ a position which is ~~center of~~ centered relative to the 6 pieces of neighboring organic EL element per ~~each~~ group.

19. (Currently Amended) A disposing method for a semiconductor element in which a unit block having a semiconductor element is disposed at a predetermined position on a base board,

the disposing method for a semiconductor element characterized in that by arranging a hole, which penetrates in ~~the~~ a thickness direction through ~~a display~~ the base board at ~~a predetermined position of the display base board~~, and by making ~~the~~ a pressure at one face of the ~~display~~ base board higher than ~~the~~ a pressure at the other face, or by drawing ~~the~~ a liquid into said hole, the unit block being disposed at a position of the hole on the base board so as to introduce the unit block ~~at the~~ to the position of said hole on one ~~surface~~ face of ~~display~~ the base board.

20. (Original) A disposing method for a semiconductor element in which a unit block having a semiconductor element is disposed at a predetermined position on a base board,

disposing method for a semiconductor element characterized in that the unit block is introduced at a predetermined position on the base board by Coulomb attractive force.

21. (Cancelled)

22. (Currently Amended) A manufacturing disposing method for a semiconductor ~~device having a process~~ element in which a unit block having a semiconductor element is disposed at a predetermined position on a base board[[:]]  
, comprising the steps of:

~~the manufacturing method for a semiconductor device the wiring and terminals for connecting with wiring inside the unit block of this wiring being formed on a base board in advance, in the unit block, at a position which contacts terminals on the base board at the time of disposing on the base board, after the terminal for connecting with the wiring on the base board being formed in advance in the unit block, and the unit block being disposed at a predetermined position on the base board.~~

disposing a plurality of unit blocks having said semiconductor element and first connecting terminals which are connected to the semiconductor element on a first base board;

disposing wirings and second connecting terminals above a second base board;

disposing each unit block on the second base board at a predetermined position so as to connect the first connecting terminals which are disposed on the unit block with the second connecting terminals which are disposed on the second base board.

23. (Cancelled)

24. (Currently Amended) A manufacturing method for a semiconductor device having a process in which a unit block having plural semiconductor elements is disposed at a predetermined position on a base board,

~~the manufacturing method for a semiconductor device in which plural terminals for each semiconductor element are disposed such that plan view of the unit block is made rectangular, and plural terminals for each organic EL elements are disposed so as to be axisymmetric relative to both center lines which are parallel with the longer side of the rectangle and center line which is parallel to the shorter side of the rectangle~~

a planar shape of the unit block being rectangular, the first connecting terminals are disposed so as to be axis symmetric with respect to center lines which are parallel with a longer side of the rectangle or a shorter side of the rectangle.

25. (Currently Amended) A manufacturing method for a semiconductor device having a process in which a unit block having plural semiconductor elements is disposed at a predetermined position on a first base board,

~~the manufacturing method for a semiconductor device the plan view of unit block being polygonal, and plural terminals for each semiconductor element being disposed along each diagonal line of this polygon, and the position of the terminals on each diagonal line being such that the same terminal is on the same previous position after the rotation~~

a planar shape of the unit block is polygonal and first connecting terminals are disposed along diagonal lines of the polygon,

and a position of the first terminals on the diagonal lines being such that the first connecting terminals are connected to the same wiring when the unit block is disposed on a second base board.

26. (Cancelled)

27. (Original) A manufacturing method for an organic EL display according to claim 25 said polygon being an equilateral polygon.

28. (Currently Amended) A manufacturing method for an active-matrix type organic EL display a light emitting layer which is inserted among at least two pieces of electrode per pixel and said light emitting layer being driven by a semiconductor element,

the manufacturing method for an active-matrix type organic EL display characterized in that the semiconductor element is formed on a base board, said semiconductor element is detached from the base board by dicing so as to be divided per unit blocks, said unit blocks of said semiconductor element is disposed on other base board.

29. (Currently Amended) A manufacturing method for an electro-optic device which is provided with ~~an electro-optic element and a semiconductor element~~ for driving an organic electro-optic which drives this electro-optic element on a display base board, for a pixel or a plurality of pixels, comprising the steps of:

~~the manufacturing method for electro-optic device comprising a process which disposes a unit block having said semiconductor element at a predetermined position of the display base board.~~

disposing a plurality of unit blocks having said semiconductor element on a first base board;

disposing each unit block, which is formed on the first base board, on a second base board such that each unit block corresponds to the pixel or the plurality of pixels formed thereon.

30. (Withdrawn) An electro-optic device which is provided with an electro-optic element and a semiconductor element which drives this electro-optic element on a display base board,

the electro-optic device characterized in that a unit block which is provided with driving circuit having said semiconductor element is disposed at a predetermined position on the display base board.

31. (Withdrawn) An electro-optic device according to claim 30 plural terminals for each electro-optic element being disposed at said unit block such that the rotational symmetry is centered at the center in plan view of said unit block.

32. (Withdrawn) An electronic device having an electro-optic device according to claim 30.

33. (Withdrawn) An electronic device having an electro-optic device according to claim 31.

34. (New) Manufacturing method for an organic EL display according to claim 10 wherein the wirings are a scanning line, a signal line, and a power supply line.

35. (New) A manufacturing method for an organic EL display according to claim 2 wherein the driving method is active-matrix method.

36. (New) A manufacturing method for an organic EL display according to claim 10 wherein the driving method is active-matrix method.